

Product Reliability/ FIT Data

March 11, 2022

Sales Name: BGA 123L4 E6327
SP-Number: SP001647052
ISPN-Number: BGA123L4
Package: PG-TSLP-4

Calculated failure rate:

FIT:	0,58
MTTF [h]:	1.713.192.451
tested devices:	10.879
device hours @ stress conditions:	15.741.497

Calculation Parameters:

Confidence Level:	60%
Activation Energy:	0,7 eV
Ambient Temperature:	55°C

FIT-rate calculations are based on JEDEC Standard JESD85 („Methods for Calculating Failure Rates in Units of FITs“).

The sample size used to calculate the FIT-rate of a product, includes also other similar products from the same product family to gain higher statistical accuracy. Within a product family all members are equal in respect to the fabrication process and technology design.

Failure Rate given in the report represents an Average Failure Rate (AFR) which relates to the component reliability.

The actual FIT-rate of the component depends on its application and may deviate from the listed FIT-rate.

Please note: AFR are shown as upper limits of the confidence interval. High failure rate may be caused by limited number of devices test

All executed reliability tests are performed according to the relevant JEDEC standards.

This FIT-rate report is not intended to be used with safety related applications and is not a base failure rate according to ISO 26262.

Provided reliability FIT-rate data are a non-binding estimation of intrinsic lifetime performance of our products.

Data update is on request only.

Disclaimer: “Document is confidential and may contain trade secrets or privileged or undisclosed information. Data may also be subject to copyright protection. Please do not copy, distribute or forward this document to anyone unless authorized by Infineon Technologies AG”.